

# TXB0101 1-Bit Bidirectional Level-Shifting and Voltage Translator With Auto Direction-Sensing and $\pm 15\text{kV}$ ESD Protection

## 1 Features

- Available in the Texas Instruments NanoFree™ package
- 1.2V to 3.6V on A port and 1.65V to 5.5V on B port ( $V_{CCA} \leq V_{CCB}$ )
- $V_{CC}$  isolation feature – if either  $V_{CC}$  input is at GND, all outputs are in the high-impedance state
- OE input circuit referenced to  $V_{CCA}$
- Low power consumption, 5 $\mu\text{A}$  maximum  $I_{CC}$
- $I_{off}$  supports partial-power-down mode operation
- Latch-up performance exceeds 100mA Per JESD 78, class II
- ESD protection Exceeds JESD 22
  - A port
    - 2000V Human body model (A114-B)
    - 250V Machine model (A115-A)
    - 1500V Charged-device model (C101)
  - B port
    - 15kV Human body model (A114-B)
    - 250V Machine model (A115-A)
    - 1500V Charged-device model (C101)

## 2 Applications

- [Handsets](#)
- [Smartphones](#)
- [Tablets](#)
- [Desktop PCs](#)

## 3 Description

This 1-bit noninverting translator uses two separate configurable power-supply rails. The A port is designed to track  $V_{CCA}$ .  $V_{CCA}$  accepts any supply voltage from 1.2V to 3.6V. The B port is designed to track  $V_{CCB}$ .  $V_{CCB}$  accepts any supply voltage from 1.65V to 5.5V. This allows for universal low-voltage bidirectional translation between any of the 1.2V, 1.5V, 1.8V, 2.5V, 3.3V, and 5V voltage nodes.  $V_{CCA}$  should not exceed  $V_{CCB}$ .

When the output-enable (OE) input is low, all outputs are placed in the high-impedance state.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

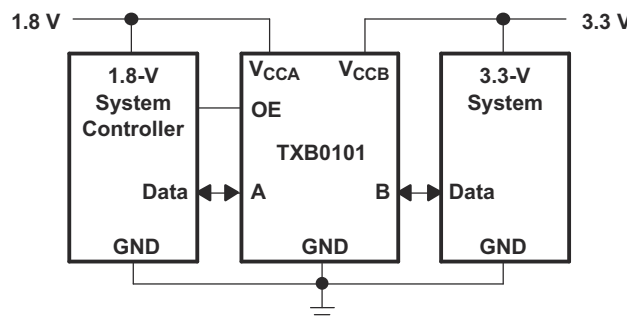
To ensure the high-impedance state during power up or power down, OE should be tied to GND through a pulldown resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

### Package Information

PART NUMBER	PACKAGE <sup>(1)</sup>	BODY SIZE (NOM)
TXB0101	SOT-23 (DBV) (6)	2.90mm × 1.60mm
	SC70 (DCK) (6)	2.00mm × 1.25mm
	SOT (DRL) (6)	1.60mm × 1.20mm
	DSBGA (YZP) (6)	0.90mm × 1.40mm
	USON (DRY) (6)	1.45mm × 1.00mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.



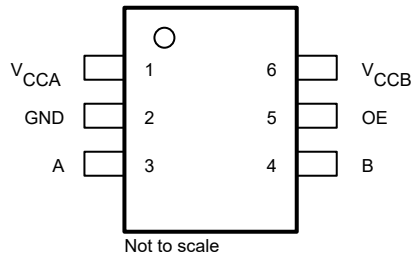
**Typical Operating Circuit**



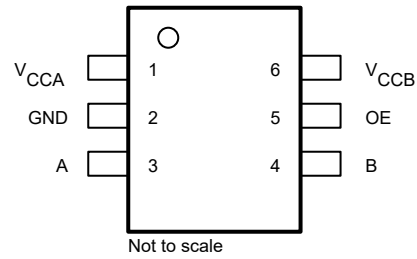
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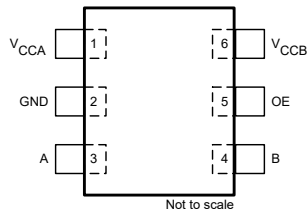
## 4 Pin Configuration and Functions



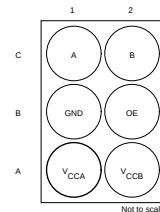
**Figure 4-1. DBV Package, 6-Pin SOT-23 (Top View)**



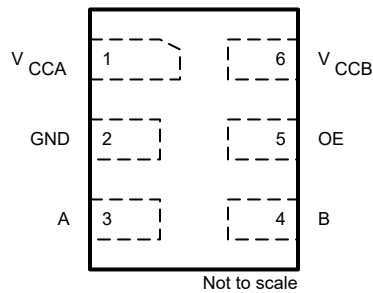
**Figure 4-2. DCK Package, 6-Pin SC70 (Top View)**



**Figure 4-3. DRL Package, 6-Pin SOT (Top View)**



**Figure 4-4. YZP Package, 6-Ball DSBGA (Bottom View)**



**Figure 4-5. DRY Package, 6-Pin USON (Top View)**

- A. See mechanical drawings for dimensions.
- B. Pullup resistors are not required on both sides for Logic I/O.
- C. If pullup or pulldown resistors are needed, the resistor value must be over 50kΩ.
- D. 50kΩ is a safe recommended value, if the customer can accept higher  $V_{OL}$  or lower  $V_{OH}$ , smaller pullup or pulldown resistor is allowed, the draft estimation is  $V_{OL} = V_{CCOUT} \times 4.5k / (4.5k + R_{PU})$  and  $V_{OH} = V_{CCOUT} \times R_{DW} / (4.5k + R_{DW})$ .
- E. If pull up resistors are needed, please refer to the TXS0101 or contact TI.
- F. For detailed information, please refer to application note, [A Guide to Voltage Translation With TXB-Type Translators](#).

**Pin Functions**

PIN		TYPE	DESCRIPTION
NO.	NAME		
1	V <sub>CCA</sub>	—	A-port supply voltage. $1.2V \leq V_{CCA} \leq 3.6V$ and $V_{CCA} \leq V_{CCB}$
2	GND	—	Ground
3	A	I/O	Input/output A. Referenced to V <sub>CCA</sub> .
4	B	I/O	Input/output B. Referenced to V <sub>CCB</sub> .
5	OE	I	3-state output enable. Pull OE low to place all outputs in 3-state mode. Referenced to V <sub>CCA</sub> .
6	V <sub>CCB</sub>	—	B-port supply voltage. $1.65V \leq V_{CCB} \leq 5.5V$

## 5 Specification

### 5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

			MIN	MAX	UNIT
V <sub>CCA</sub>	Supply voltage		–0.5	4.6	V
V <sub>CCB</sub>	Supply voltage		–0.5	6.5	
V <sub>I</sub>	Input voltage <sup>(2)</sup>		–0.5	6.5	V
V <sub>O</sub>	Voltage applied to any output in the high-impedance or power-off state <sup>(2)</sup>		–0.5	6.5	V
V <sub>O</sub>	Voltage applied to any output in the high or low state <sup>(2) (3)</sup>	A port	–0.5	V <sub>CCA</sub> + 0.5	V
		B port	–0.5	V <sub>CCB</sub> + 0.5	
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0		–50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		–50	mA
I <sub>O</sub>	Continuous output current			±50	mA
	Continuous current through V <sub>CCA</sub> , V <sub>CCB</sub> , or GND			±100	mA
T <sub>JMAX</sub>	Absolute maximum junction temperature			150	°C
T <sub>stg</sub>	Storage temperature		–65	150	°C

- (1) Operation outside the *Absolute Maximum Ratings* may cause permanent device damage. *Absolute Maximum Ratings* do not imply functional operation of the device at these or any other conditions beyond those listed under *Recommended Operating Conditions*. If used outside the *Recommended Operating Conditions* but within the *Absolute Maximum Ratings*, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime
- (2) The input and output negative Voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V<sub>CCA</sub> and V<sub>CCB</sub> are provided in the recommended operating conditions table.

### 5.2 ESD Ratings

			VALUE	UNIT
TXB0101 Port A				
V <sub>(ESD)</sub>	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±2000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	±1500	
TXB0101 Port B				
V <sub>(ESD)</sub>	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±15	kV
		Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	±1500	V

- (1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

### 5.3 Recommended Operating Conditions

See (1) (2).

			V <sub>CCA</sub>	V <sub>CCB</sub>	MIN	MAX	UNIT
V <sub>CCA</sub>	Supply voltage				1.2	3.6	V
V <sub>CCB</sub>					1.65	5.5	
V <sub>IH</sub>	High-level input voltage	Data inputs	1.2V to 3.6V	1.65V to 5.5V	V <sub>CCI</sub> × 0.65 <sup>(3)</sup>	V <sub>CCI</sub>	V
		OE	1.2V to 3.6V	1.65V to 5.5V	V <sub>CCA</sub> × 0.65	5.5	
V <sub>IL</sub>	Low-level input voltage	Data inputs	1.2V to 5.5V	1.65V to 5.5V	0	V <sub>CCI</sub> × 0.35 <sup>(3)</sup>	V
		OE	1.2V to 3.6V	1.65V to 5.5V	0	V <sub>CCA</sub> × 0.35	
Δt/Δv	Input transition rise or fall rate	A-port inputs	1.2V to 3.6V	1.65V to 5.5V	40		ns/V
		B-port inputs	1.2V to 3.6V	1.65V to 3.6V	40		
				4.5V to 5.5V	30		
T <sub>A</sub>	Operating free-air temperature				−40	85	°C

(1) The A and B sides of an unused data I/O pair must be held in the same state, i.e., both at V<sub>CCI</sub> or both at GND.

(2) V<sub>CCA</sub> must be less than or equal to V<sub>CCB</sub> and must not exceed 3.6V.

(3) V<sub>CCI</sub> is the supply voltage associated with the input port.

### 5.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		TXB0101					UNIT
		DBV (SOT-23)	DCK (SC70)	DRL (SOT)	YZP (DSBGA)	DRY (USON)	
		6 PINS	6 PINS	6 PINS	6 PINS	6 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	192.3	266.9	204.2	105.8	277.6	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	164.8	80.4	76.4	1.6	163.1	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	38.6	99.1	38.7	10.8	158.9	°C/W
ψ <sub>JT</sub>	Junction-to-top characterization parameter	43.7	1.5	3.4	3.1	29.3	°C/W
ψ <sub>JB</sub>	Junction-to-board characterization parameter	38.1	98.3	38.5	10.8	158.2	°C/W
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	N/A	N/A	N/A	N/A	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application note.

## 5.5 Electrical Characteristics (DRY)

over recommended operating free-air temperature range (unless otherwise noted)<sup>(1) (2)</sup>

PARAMETER		TEST CONDITIONS	V <sub>CCA</sub>	V <sub>CCB</sub>	T <sub>A</sub> = 25°C			–40°C to 85°C			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	
V <sub>OHA</sub>		I <sub>OH</sub> = –20μA	1.2V		1.1			V <sub>CCA</sub> – 0.4			V
			1.4V to 3.6V								
V <sub>OLA</sub>		I <sub>OL</sub> = 20μA	1.2V		0.9			0.4			V
			1.4V to 3.6V								
V <sub>OHB</sub>		I <sub>OH</sub> = –20μA		1.65V to 5.5V				V <sub>CCB</sub> – 0.4			V
V <sub>OLB</sub>		I <sub>OL</sub> = 20μA		1.65V to 5.5V				0.4			V
I <sub>I</sub>	OE		1.2V to 3.6V	1.65V to 5.5V	±1						±2 μA
I <sub>off</sub>	A port		0V	0V to 5.5V	±1						±2 μA
	B port		0V to 3.6V	0V	±1						±2 μA
I <sub>OZ</sub>	A or B port	OE = GND	1.2V to 3.6V	1.65V to 5.5V	±1						±2 μA
I <sub>CCA</sub>		V <sub>I</sub> = V <sub>CCI</sub> or GND, I <sub>O</sub> = 0	1.2V	1.65V to 5.5V	0.2						μA
			1.4V to 3.6V	1.65V to 5.5V				3			
			3.6V	0V				2			
			0V	5.5V				–2			
I <sub>CCB</sub>		V <sub>I</sub> = V <sub>CCI</sub> or GND, I <sub>O</sub> = 0	1.2V	1.65V to 5.5V	3.4						μA
			1.4V to 3.6V	1.65V to 5.5V				5			
			3.6V	0V				–2			
			0V	5.5V				2			
I <sub>CCA</sub> + I <sub>CCB</sub>		V <sub>I</sub> = V <sub>CCI</sub> or GND, I <sub>O</sub> = 0	1.2V	1.65V to 5.5V	3.5						μA
			1.4V to 3.6V	1.65V to 5.5V				8			
I <sub>CCZA</sub>		V <sub>I</sub> = V <sub>CCI</sub> or GND, I <sub>O</sub> = 0, OE = GND	1.2V	1.65V to 5.5V	0.2						μA
			1.4V to 3.6V	1.65V to 5.5V				3			
I <sub>CCZB</sub>		V <sub>I</sub> = V <sub>CCI</sub> or GND, I <sub>O</sub> = 0, OE = GND	1.2V	1.65V to 5.5V	3.3						μA
			1.4V to 3.6V	1.65V to 5.5V				5			
C <sub>i</sub>	OE		1.2V to 3.6V	1.65V to 5.5V	2.5						3 pF
C <sub>io</sub>	A port		1.2V to 3.6V	1.65V to 5.5V	5						6 pF
	B port				11			14.5			

## 5.6 Electrical Characteristics (Other Packages)

over recommended operating free-air temperature range (unless otherwise noted)<sup>(1) (2)</sup>

PARAMETER		TEST CONDITIONS	V <sub>CCA</sub>	V <sub>CCB</sub>	T <sub>A</sub> = 25°C			–40°C to 85°C			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	
V <sub>OHA</sub>		I <sub>OH</sub> = –20μA	1.2V		1.1			V <sub>CCA</sub> – 0.4			V
			1.4V to 3.6V								
V <sub>OLA</sub>		I <sub>OL</sub> = 20μA	1.2V		0.9			0.4			V
			1.4V to 3.6V								
V <sub>OHB</sub>		I <sub>OH</sub> = –20μA		1.65V to 5.5V				V <sub>CCB</sub> – 0.4			V
V <sub>OLB</sub>		I <sub>OL</sub> = 20μA		1.65V to 5.5V				0.4			V
I <sub>I</sub>	OE		1.2V to 3.6V	1.65V to 5.5V	±1			±2			μA
I <sub>off</sub>	A port		0V	0V to 5.5V	±1			±2			μA
	B port		0V to 3.6V	0V	±1			±2			
I <sub>OZ</sub>	A or B port	OE = GND	1.2V to 3.6V	1.65V to 5.5V	±1			±2			μA
I <sub>CCA</sub>		V <sub>I</sub> = V <sub>CCI</sub> or GND, I <sub>O</sub> = 0	1.2V	1.65V to 5.5V	0.06			3 2 –2			μA
			1.4V to 3.6V	1.65V to 5.5V							
			3.6V	0V							
			0V	5.5V							
I <sub>CCB</sub>		V <sub>I</sub> = V <sub>CCI</sub> or GND, I <sub>O</sub> = 0	1.2V	1.65V to 5.5V	3.4			5 –2 2			μA
			1.4V to 3.6V	1.65V to 5.5V							
			3.6V	0V							
			0V	5.5V							
I <sub>CCA</sub> + I <sub>CCB</sub>		V <sub>I</sub> = V <sub>CCI</sub> or GND, I <sub>O</sub> = 0	1.2V	1.65V to 5.5V	3.5			8			μA
			1.4V to 3.6V	1.65V to 5.5V							
I <sub>CCZA</sub>		V <sub>I</sub> = V <sub>CCI</sub> or GND, I <sub>O</sub> = 0, OE = GND	1.2V	1.65V to 5.5V	0.05			3			μA
			1.4V to 3.6V	1.65V to 5.5V							
I <sub>CCZB</sub>		V <sub>I</sub> = V <sub>CCI</sub> or GND, I <sub>O</sub> = 0, OE = GND	1.2V	1.65V to 5.5V	3.3			5			μA
			1.4V to 3.6V	1.65V to 5.5V							
C <sub>i</sub>	OE		1.2V to 3.6V	1.65V to 5.5V	2.5			3			pF
C <sub>io</sub>	A port		1.2V to 3.6V	1.65V to 5.5V	5			6			pF
	B port				11			13			

(1) V<sub>CCI</sub> is the supply voltage associated with the input port.

(2) V<sub>CCO</sub> is the supply voltage associated with the output port.



## 5.7 Timing Requirements, $V_{CCA} = 1.2V$

$T_A = 25^\circ C$ ,  $V_{CCA} = 1.2V$

			$V_{CCB} = 1.8V$	$V_{CCB} = 2.5V$	$V_{CCB} = 3.3V$	$V_{CCB} = 5V$	UNIT
			TYP	TYP	TYP	TYP	
Data rate			20	20	20	20	Mbps
$t_w$	Pulse duration	Data inputs	50	50	50	50	ns

## 5.8 Timing Requirements, $V_{CCA} = 1.5V \pm 0.1V$

over recommended operating free-air temperature range,  $V_{CCA} = 1.5V \pm 0.1V$  (unless otherwise noted)

			$V_{CCB} = 1.8V \pm 0.15V$		$V_{CCB} = 2.5V \pm 0.2V$		$V_{CCB} = 3.3V \pm 0.3V$		$V_{CCB} = 5V \pm 0.5V$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
Data rate			40		40		40		40		Mbps
$t_w$	Pulse duration	Data inputs	25		25		25		25		ns

## 5.9 Timing Requirements, $V_{CCA} = 1.8V \pm 0.15V$

over recommended operating free-air temperature range,  $V_{CCA} = 1.8V \pm 0.15V$  (unless otherwise noted)

			$V_{CCB} = 1.8V \pm 0.15V$		$V_{CCB} = 2.5V \pm 0.2V$		$V_{CCB} = 3.3V \pm 0.3V$		$V_{CCB} = 5V \pm 0.5V$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
Data rate			60		60		60		60		Mbps
$t_w$	Pulse duration	Data inputs	17		17		17		17		ns

## 5.10 Timing Requirements, $V_{CCA} = 2.5V \pm 0.2V$

over recommended operating free-air temperature range,  $V_{CCA} = 2.5V \pm 0.2V$  (unless otherwise noted)

			$V_{CCB} = 2.5V \pm 0.2V$		$V_{CCB} = 3.3V \pm 0.3V$		$V_{CCB} = 5V \pm 0.5V$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
Data rate			100		100		100		Mbps
$t_w$	Pulse duration	Data inputs	10		10		10		ns

## 5.11 Timing Requirements, $V_{CCA} = 3.3V \pm 0.3V$

over recommended operating free-air temperature range,  $V_{CCA} = 3.3V \pm 0.3V$  (unless otherwise noted)

			$V_{CCB} = 3.3V \pm 0.3V$		$V_{CCB} = 5V \pm 0.5V$		UNIT
			MIN	MAX	MIN	MAX	
Data rate			100		100		Mbps
$t_w$	Pulse duration	Data inputs	10		10		ns

## 5.12 Switching Characteristics, $V_{CCA} = 1.2V$ (DRY)

$T_A = 25^\circ C$ ,  $V_{CCA} = 1.2V$

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.8V$	$V_{CCB} = 2.5V$	$V_{CCB} = 3.3V$	$V_{CCB} = 5V$	UNIT
			TYP	TYP	TYP	TYP	
$t_{pd}$	A	B	6.9	5.7	5.3	5.5	ns
	B	A	7.4	6.4	6	5.8	
$t_{en}$	OE	A	1	1	1	1	$\mu s$
		B	1	1	1	1	
$t_{dis}$	OE	A	392	392	392	392	ns
		B	392	392	392	392	
$t_{rA}, t_{fA}$	A-port rise and fall times		4.2	4.2	4.2	4.2	ns
$t_{rB}, t_{fB}$	B-port rise and fall times		2.1	1.5	1.2	1.1	ns
Max data rate			20	20	20	20	Mbps

## 5.13 Switching Characteristics, $V_{CCA} = 1.2V$ (Other Packages)

$T_A = 25^\circ C$ ,  $V_{CCA} = 1.2V$

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.8V$	$V_{CCB} = 2.5V$	$V_{CCB} = 3.3V$	$V_{CCB} = 5V$	UNIT
			TYP	TYP	TYP	TYP	
$t_{pd}$	A	B	6.9	5.7	5.3	5.5	ns
	B	A	7.4	6.4	6	5.8	
$t_{en}$	OE	A	1	1	1	1	$\mu s$
		B	1	1	1	1	
$t_{dis}$	OE	A	18	15	14	14	ns
		B	20	17	16	16	
$t_{rA}, t_{fA}$	A-port rise and fall times		4.2	4.2	4.2	4.2	ns
$t_{rB}, t_{fB}$	B-port rise and fall times		2.1	1.5	1.2	1.1	ns
Max data rate			20	20	20	20	Mbps

## 5.14 Switching Characteristics, $V_{CCA} = 1.5V \pm 0.1V$ (DRY)

over recommended operating free-air temperature range,  $V_{CCA} = 1.5V \pm 0.1V$  (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.8V \pm 0.15V$		$V_{CCB} = 2.5V \pm 0.2V$		$V_{CCB} = 3.3V \pm 0.3V$		$V_{CCB} = 5V \pm 0.5V$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	B	1.4	12.9	1.2	10.1	1.1	10	0.8	9.9	ns
	B	A	0.9	14.2	0.7	12	0.4	11.7	0.3	13.7	
$t_{en}$	OE	A		1		1		1		1	$\mu s$
		B		1		1		1		1	
$t_{dis}$	OE	A	278	390	236	305	236	305	236	305	ns
		B	278	390	236	305	236	305	236	305	
$t_{rA}, t_{fA}$	A-port rise and fall times		1.4	5.1	1.4	5.1	1.4	5.1	1.4	5.1	ns
$t_{rB}, t_{fB}$	B-port rise and fall times		0.9	4.5	0.6	3.2	0.5	2.8	0.4	2.7	ns
Max data rate			40		40		40		40		Mbps

### 5.15 Switching Characteristics, $V_{CCA} = 1.5V \pm 0.1V$ (Other Packages)

over recommended operating free-air temperature range,  $V_{CCA} = 1.5V \pm 0.1V$  (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.8V \pm 0.15V$		$V_{CCB} = 2.5V \pm 0.2V$		$V_{CCB} = 3.3V \pm 0.3V$		$V_{CCB} = 5V \pm 0.5V$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	B	1.4	12.9	1.2	10.1	1.1	10	0.8	9.9	ns
	B	A	0.9	14.2	0.7	12	0.4	11.7	0.3	13.7	
$t_{en}$	OE	A		1		1		1		1	$\mu s$
		B		1		1		1		1	
$t_{dis}$	OE	A	5.9	31	5.7	25.9	5.6	23	5.7	22.4	ns
		B	5.4	30.3	4.9	22.8	4.8	20	4.9	19.5	
$t_{rA}, t_{fA}$	A-port rise and fall times		1.4	5.1	1.4	5.1	1.4	5.1	1.4	5.1	ns
$t_{rB}, t_{fB}$	B-port rise and fall times		0.9	4.5	0.6	3.2	0.5	2.8	0.4	2.7	ns
Max data rate			40		40		40		40		Mbps

### 5.16 Switching Characteristics, $V_{CCA} = 1.8V \pm 0.15V$ (DRY)

over recommended operating free-air temperature range,  $V_{CCA} = 1.8V \pm 0.15V$  (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.8V \pm 0.15V$		$V_{CCB} = 2.5V \pm 0.2V$		$V_{CCB} = 3.3V \pm 0.3V$		$V_{CCB} = 5V \pm 0.5V$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	B	1.6	11	1.4	7.7	1.3	6.8	1.2	6.5	ns
	B	A	1.5	12	1.3	8.4	1	7.6	0.9	7.1	
$t_{en}$	OE	A		1		1		1		1	$\mu s$
		B		1		1		1		1	
$t_{dis}$	OE	A	278	389	191	253	190	248	189	248	ns
		B	278	389	191	253	190	248	189	248	
$t_{rA}, t_{fA}$	A-port rise and fall times		1	4.2	1.1	4.1	1.1	4.1	1.1	4.1	ns
$t_{rB}, t_{fB}$	B-port rise and fall times		0.9	4.5	0.6	3.2	0.5	2.8	0.4	2.7	ns
Max data rate			60		60		60		60		Mbps

### 5.17 Switching Characteristics, $V_{CCA} = 1.8V \pm 0.15V$ (Other Packages)

over recommended operating free-air temperature range,  $V_{CCA} = 1.8V \pm 0.15V$  (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 1.8V \pm 0.15V$		$V_{CCB} = 2.5V \pm 0.2V$		$V_{CCB} = 3.3V \pm 0.3V$		$V_{CCB} = 5V \pm 0.5V$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	B	1.6	11	1.4	7.7	1.3	6.8	1.2	6.5	ns
	B	A	1.5	12	1.3	8.4	1	7.6	0.9	7.1	
$t_{en}$	OE	A		1		1		1		1	$\mu s$
		B		1		1		1		1	
$t_{dis}$	OE	A	5.9	31	5.1	21.3	5	19.3	5	17.4	ns
		B	5.4	30.3	4.4	20.8	4.2	17.9	4.3	16.3	
$t_{rA}, t_{fA}$	A-port rise and fall times		1	4.2	1.1	4.1	1.1	4.1	1.1	4.1	ns
$t_{rB}, t_{fB}$	B-port rise and fall times		0.9	4.5	0.6	3.2	0.5	2.8	0.4	2.7	ns
Max data rate			60		60		60		60		Mbps

### 5.18 Switching Characteristics, $V_{CCA} = 2.5V \pm 0.2V$ (DRY)

over recommended operating free-air temperature range,  $V_{CCA} = 2.5V \pm 0.2V$  (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 2.5V \pm 0.2V$		$V_{CCB} = 3.3V \pm 0.3V$		$V_{CCB} = 5V \pm 0.5V$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	B	1.1	6.3	1	5.2	0.9	4.7	ns
	B	A	1.2	6.6	1.1	5.1	0.9	4.4	
$t_{en}$	OE	A		1		1		1	$\mu s$
		B		1		1		1	
$t_{dis}$	OE	A	190	252	137	184	133	169	ns
		B	190	252	137	184	133	169	
$t_{rA}, t_{fA}$	A-port rise and fall times		0.8	3	0.8	3	0.8	3	ns
$t_{rB}, t_{fB}$	B-port rise and fall times		0.7	3	0.5	2.8	0.4	2.7	ns
Max data rate			100		100		100		Mbps

### 5.19 Switching Characteristics, $V_{CCA} = 2.5V \pm 0.2V$ (Other Packages)

over recommended operating free-air temperature range,  $V_{CCA} = 2.5V \pm 0.2V$  (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 2.5V \pm 0.2V$		$V_{CCB} = 3.3V \pm 0.3V$		$V_{CCB} = 5V \pm 0.5V$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	B	1.1	6.3	1	5.2	0.9	4.7	ns
	B	A	1.2	6.6	1.1	5.1	0.9	4.4	
$t_{en}$	OE	A		1		1		1	$\mu s$
		B		1		1		1	
$t_{dis}$	OE	A	5.1	21.3	4.6	15.2	4.6	13.2	ns
		B	4.4	20.8	3.8	16	3.9	13.9	
$t_{rA}, t_{fA}$	A-port rise and fall times		0.8	3	0.8	3	0.8	3	ns
$t_{rB}, t_{fB}$	B-port rise and fall times		0.7	3	0.5	2.8	0.4	2.7	ns
Max data rate			100		100		100		Mbps

### 5.20 Switching Characteristics, $V_{CCA} = 3.3V \pm 0.3V$ (DRY)

over recommended operating free-air temperature range,  $V_{CCA} = 3.3V \pm 0.3V$  (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 3.3V \pm 0.3V$		$V_{CCB} = 5V \pm 0.5V$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}$	A	B	0.9	4.7	0.8	4	ns
	B	A	1	4.9	0.9	4.5	
$t_{en}$	OE	A		1		1	$\mu s$
		B		1		1	
$t_{dis}$	OE	A	137	183	97.6	127	ns
		B	137	183	97.6	127	
$t_{rA}, t_{fA}$	A-port rise and fall times		0.7	2.5	0.7	2.5	ns
$t_{rB}, t_{fB}$	B-port rise and fall times		0.5	2.3	0.4	2.7	ns
Max data rate			100		100		Mbps

## 5.21 Switching Characteristics, $V_{CCA} = 3.3V \pm 0.3V$ (Other Packages)

over recommended operating free-air temperature range,  $V_{CCA} = 3.3V \pm 0.3V$  (unless otherwise noted)

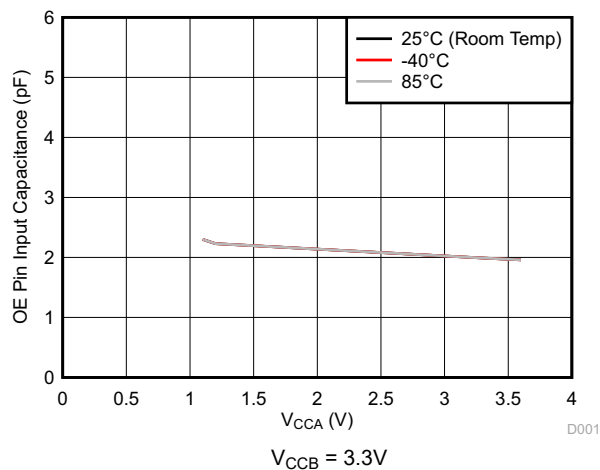
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CCB} = 3.3V \pm 0.3V$		$V_{CCB} = 5V \pm 0.5V$		UNIT
			MIN	MAX	MIN	MAX	
$t_{pd}$	A	B	0.9	4.7	0.8	4	ns
	B	A	1	4.9	0.9	4.5	
$t_{en}$	OE	A		1		1	$\mu s$
		B		1		1	
$t_{dis}$	OE	A	4.6	15.2	4.3	12.1	ns
		B	3.8	16	3.4	13.2	
$t_{rA}, t_{fA}$	A-port rise and fall times		0.7	2.5	0.7	2.5	ns
$t_{rB}, t_{fB}$	B-port rise and fall times		0.5	2.3	0.4	2.7	ns
Max data rate			100		100		Mbps

## 5.22 Operating Characteristics

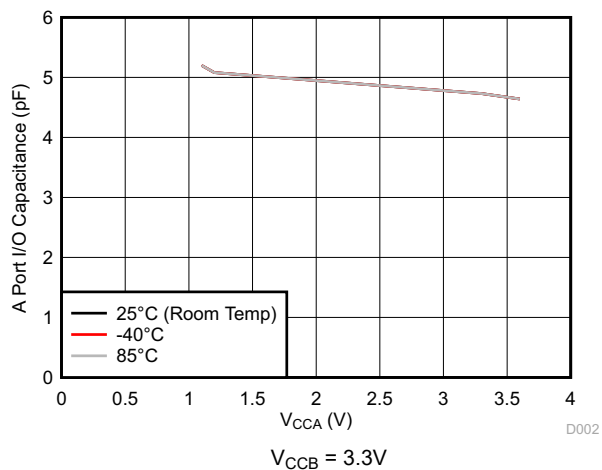
$T_A = 25^\circ C$

PARAMETER		TEST CONDITIONS	V <sub>CCA</sub>							UNIT
			1.2V	1.2V	1.5V	1.8V	2.5V	2.5V	3.3V	
			V <sub>CCB</sub>							
			5V	1.8V	1.8V	1.8V	2.5V	5V	3.3V to 5V	
			TYP	TYP	TYP	TYP	TYP	TYP	TYP	
C <sub>pdA</sub>	A-port input, B-port output	C <sub>L</sub> = 0, f = 10MHz, t <sub>r</sub> = t <sub>f</sub> = 1ns, OE = V <sub>CCA</sub> (outputs enabled)	7.8	8	8	7	7	8	8	pF
	B-port input, A-port output		12	11	11	11	11	11	11	
C <sub>pdB</sub>	A-port input, B-port output		38.1	28	29	29	29	29	30	
	B-port input, A-port output		25.4	18	17	17	18	20	21	
C <sub>pdA</sub>	A-port input, B-port output	C <sub>L</sub> = 0, f = 10MHz, t <sub>r</sub> = t <sub>f</sub> = 1ns, OE = GND (outputs disabled)	0.01	0.01	0.01	0.01	0.01	0.01	0.01	pF
	B-port input, A-port output		0.01	0.01	0.01	0.01	0.01	0.01	0.01	
C <sub>pdB</sub>	A-port input, B-port output		0.01	0.01	0.01	0.01	0.01	0.01	0.02	
	B-port input, A-port output		0.01	0.01	0.01	0.01	0.01	0.01	0.03	

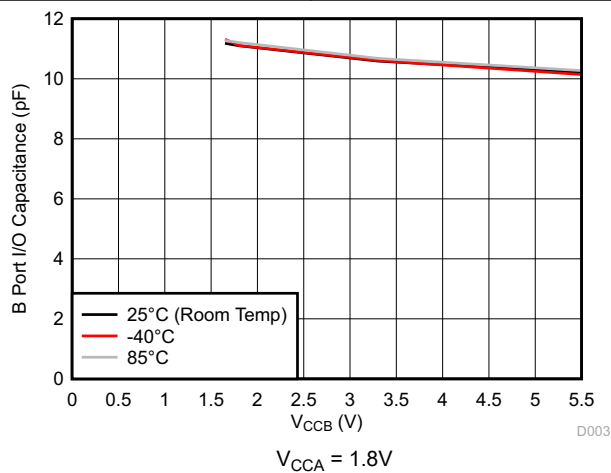
## 5.23 Typical Characteristics



**Figure 5-1. Input Capacitance for OE pin ( $C_i$ ) vs Power Supply ( $V_{CCA}$ )**

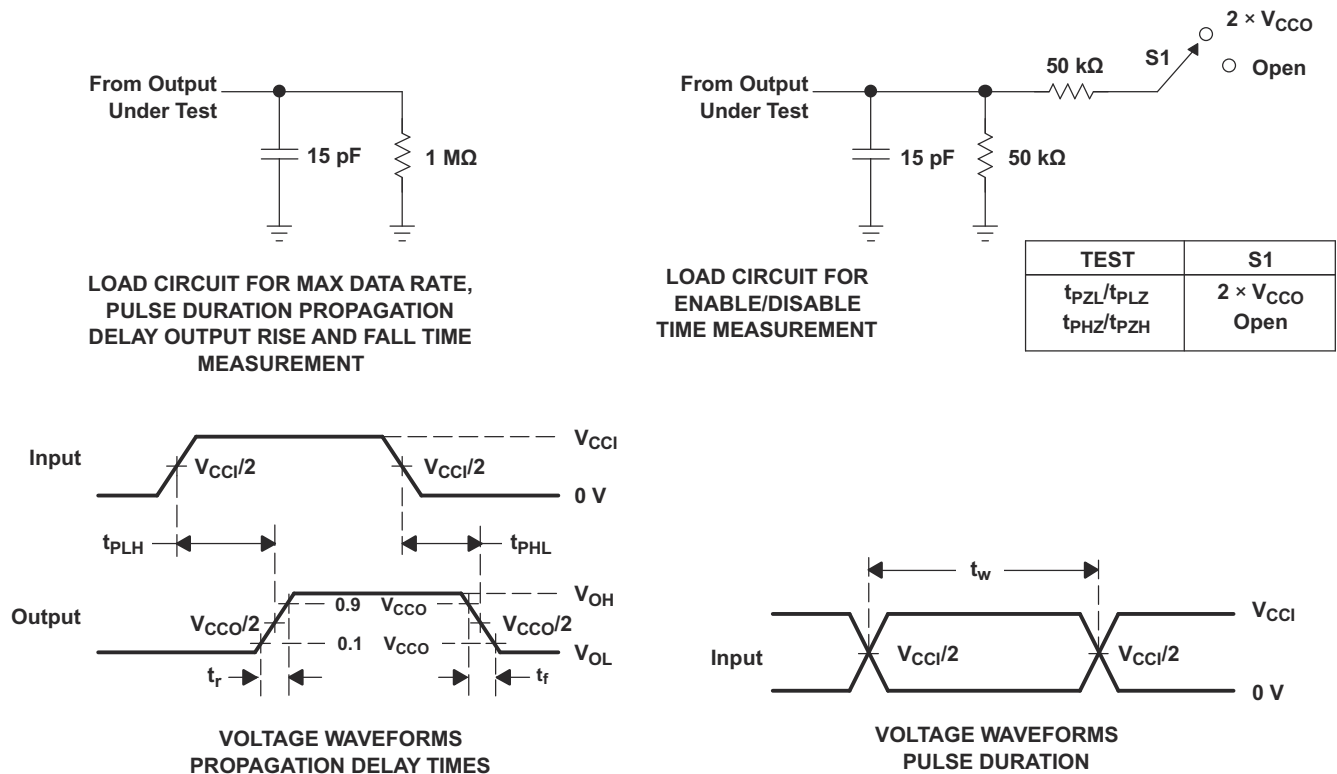


**Figure 5-2. Capacitance for A Port I/O Pins ( $C_{IO}$ ) vs Power Supply ( $V_{CCA}$ )**



**Figure 5-3. Capacitance for B Port I/O Pins ( $C_{IO}$ ) vs Power Supply ( $V_{CCB}$ )**

## Parameter Measurement Information



- A.  $C_L$  includes probe and jig capacitance.
- B. All input pulses are supplied by generators having the following characteristics: PRR = 10 MHz,  $Z_O = 50 \Omega$ ,  $dv/dt \geq 1$  V/ns.
- C. The outputs are measured one at a time, with one transition per measurement.
- D.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- E.  $V_{CCI}$  is the  $V_{CC}$  associated with the input port.
- F.  $V_{CCO}$  is the  $V_{CC}$  associated with the output port.
- G. All parameters and waveforms are not applicable to all devices.

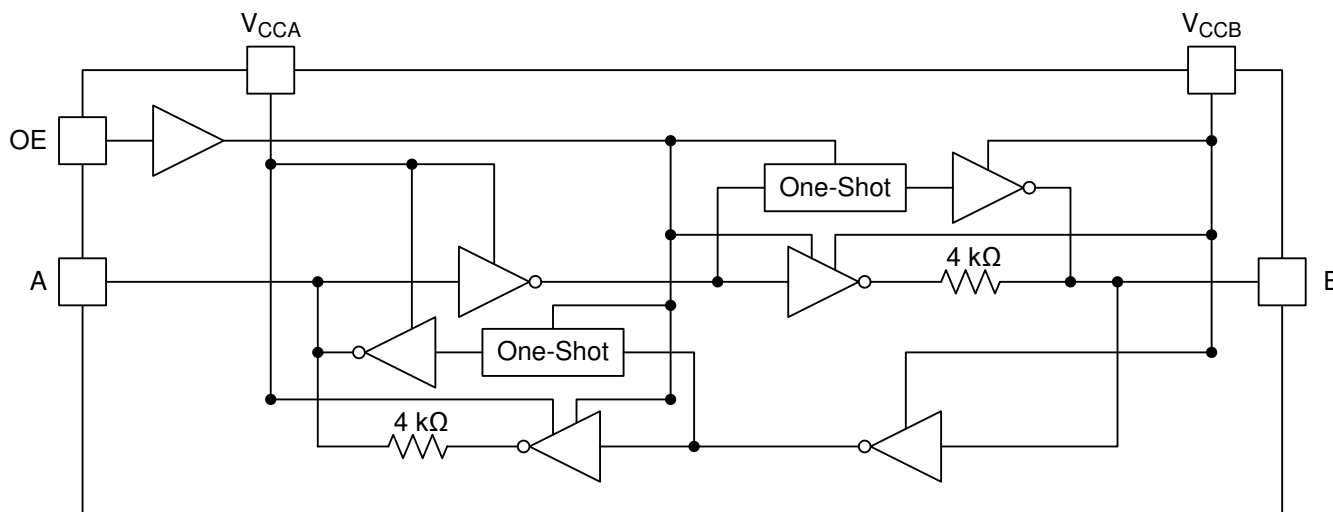
**Figure 6-1. Load Circuits and Voltage Waveforms**

## 6 Detailed Description

### 6.1 Overview

The TXB0101 device is a 1-bit directionless level-shifting and voltage translator specifically designed for translating logic voltage levels. The A port accepts I/O voltages ranging from 1.2V to 3.6V, while the B port is able to accept I/O voltages from 1.65V to 5.5V. The device is a buffered architecture with edge rate accelerators (one-shots) to improve the overall data rate. This device can only translate push-pull CMOS logic outputs. If for open-drain signal translation, see TI [TXS010X](#) products.

### 6.2 Functional Block Diagram



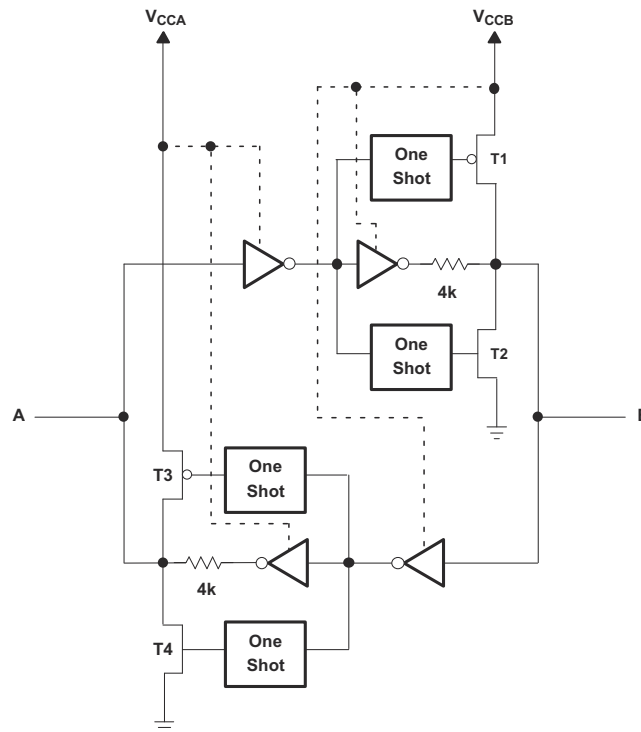
### 6.3 Feature Description

#### 6.3.1 Architecture

The TXB0101 architecture (see [Figure 6-1](#)) does not require a direction-control signal to control the direction of data flow from A to B or from B to A. In a DC state, the output drivers of the TXB0101 can maintain a high or low, but are designed to be weak, so that they can be overdriven by an external driver when data on the bus starts flowing the opposite direction.

The output one-shots detect rising or falling edges on the A or B ports. During a rising edge, the one-shot turns on the PMOS transistors (T1, T3) for a short duration, which speeds up the low-to-high transition. Similarly, during a falling edge, the one-shot turns on the NMOS transistors (T2, T4) for a short duration, which speeds up the high-to-low transition. The typical output impedance during output transition is 70Ω at  $V_{CCO} = 1.2V$  to 1.8V, 50Ω at  $V_{CCO} = 1.8V$  to 3.3V, and 40 Ω at  $V_{CCO} = 3.3V$  to 5V.





**Figure 6-1. Architecture of TXB0101 I/O Cell**

### 6.3.2 Power Up

During operation, make sure that  $V_{CCA} \leq V_{CCB}$  at all times. During power up sequencing,  $V_{CCA} \geq V_{CCB}$  does not damage the device, so any power supply can be ramped up first. The TXB0101 has circuitry that disables all output ports when either  $V_{CC}$  is switched off ( $V_{CCA/B} = 0V$ ) and are placed in high-impedance state.

### 6.3.3 Enable and Disable

The TXB0101 has an OE input that is used to disable the device by setting OE = low, which places all I/Os in the high-impedance (Hi-Z) state. The disable time ( $t_{dis}$ ) indicates the delay between when OE goes low and when the outputs are actually disabled (Hi-Z). The enable time ( $t_{en}$ ) indicates the amount of time the user must allow for the one-shot circuitry to become operational after OE is taken high.

### 6.3.4 Pullup or Pulldown Resistors on I/O Lines

The TXB0101 is designed to drive capacitive loads of up to 70pF. The output drivers of the TXB0101 have low-DC drive strength. If pullup or pulldown resistors are connected externally to the data I/Os, their values must be kept higher than 50kΩ to make sure they do not contend with the output drivers of the TXB0101.

For the same reason, the TXB0101 should not be used in applications such as I<sup>2</sup>C or 1-Wire where an open-drain driver is connected on the bidirectional data I/O. For these applications, use a device from the TI [TXS010X](#) series of level translators.

## 6.4 Device Functional Modes

The TXB0101 device has two functional modes, enabled and disabled. To disable the device set the OE input low, which places all I/Os in a high-impedance state. Setting the OE input high enables the device.

## 7 Application and Implementation

### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 7.1 Application Information

The TXB0101 can be used in level-translation applications for interfacing devices or systems operating at different interface voltages with one another. It can only translate push-pull CMOS logic outputs. If for open-drain signal translation, see TI [TXS010X](#) products. Any external pulldown or pullup resistors are recommended larger than 50kΩ.

### 7.2 Typical Application

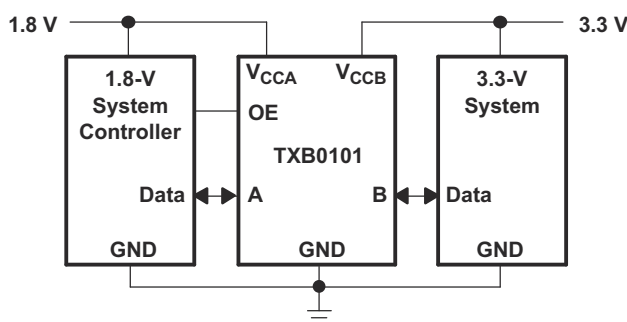


Figure 7-1. Typical Application Circuit

#### 7.2.1 Design Requirements

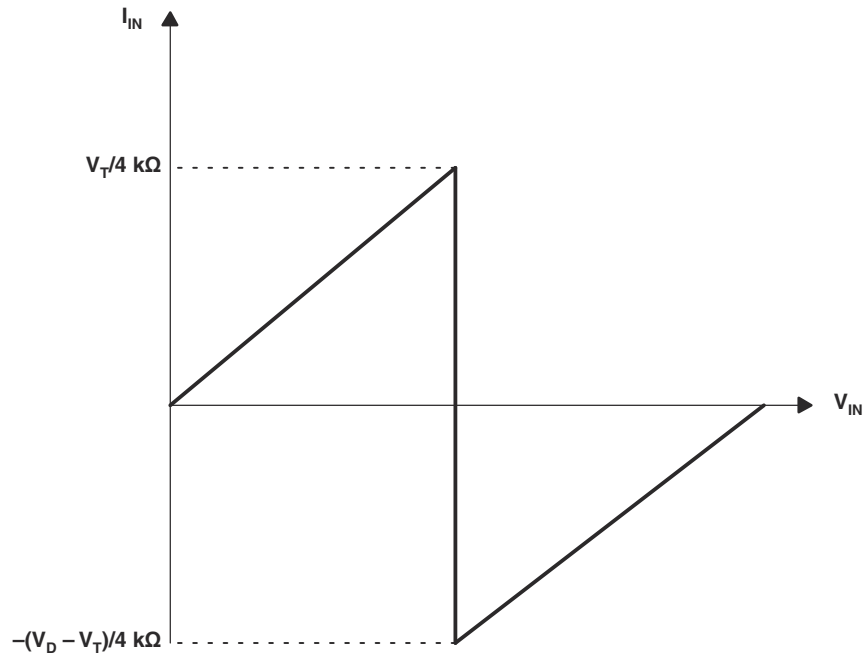
For this design example, use the parameters listed in [Table 7-1](#). And make sure that  $V_{CCA} \leq V_{CCB}$ .

Table 7-1. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
Input voltage range	1.2V to 3.6V
Output voltage range	1.65V to 5.5V

##### 7.2.1.1 Input Driver Requirements

Typical  $I_{IN}$  vs  $V_{IN}$  characteristics of the TXB0101 are shown in [Figure 7-2](#). For proper operation, the device driving the data I/Os of the TXB0101 must have drive strength of at least  $\pm 2\text{mA}$ .



- A.  $V_T$  is the input threshold voltage of the TXB0101 (typically  $V_{CC}/2$ ).  
B.  $V_D$  is the supply voltage of the external driver.

**Figure 7-2. Typical  $I_{IN}$  vs  $V_{IN}$  Curve**

### 7.2.2 Detailed Design Procedure

To begin the design process, determine the following:

- Input voltage range
  - Use the supply voltage of the device that is driving the TXB0101 device to determine the input voltage range. For a valid logic HIGH the value must exceed the  $V_{IH}$  of the input port. For a valid logic LOW the value must be less than the  $V_{IL}$  of the input port.
- Output voltage range
  - Use the supply voltage of the device that the TXB0101 device is driving to determine the output voltage range.
  - External pullup or pulldown resistors are not recommended. If mandatory, TI recommends the value should be larger than 50kΩ.
- An external pulldown or pullup resistor decreases the output  $V_{OH}$  and  $V_{OL}$ . Use [Equation 1](#) and [Equation 2](#) to draft estimate the  $V_{OH}$  and  $V_{OL}$  as a result of an external pulldown and pullup resistor.

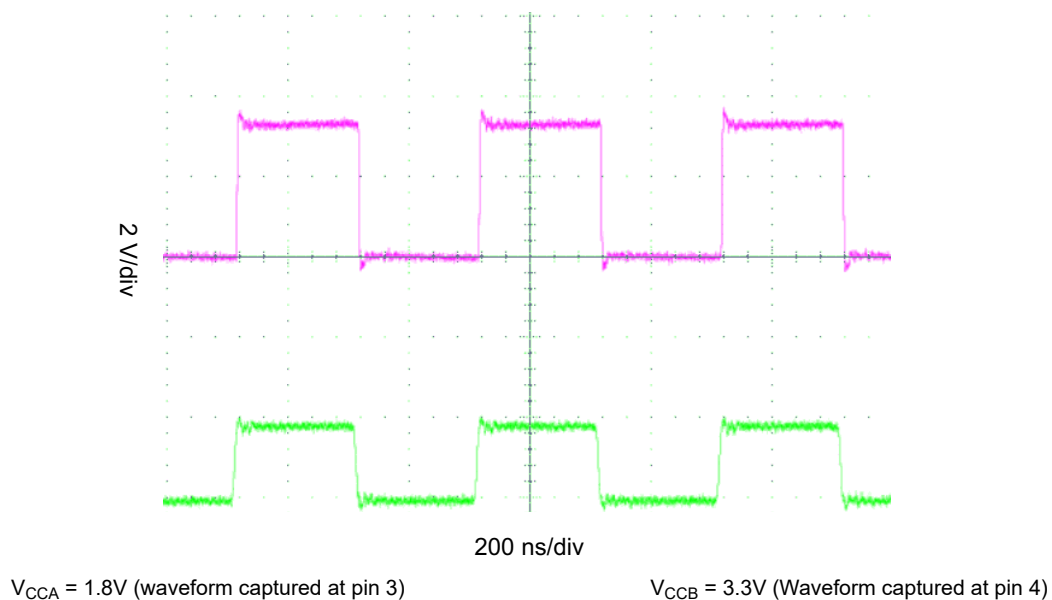
$$V_{OH} = V_{CCx} \times R_{PD} / (R_{PD} + 4.5k\Omega) \quad (1)$$

$$V_{OL} = V_{CCx} \times 4.5k\Omega / (R_{PU} + 4.5k\Omega) \quad (2)$$

where

- $V_{CCx}$  is the output port supply voltage on either  $V_{CCA}$  or  $V_{CCB}$
- $R_{PD}$  is the value of the external pulldown resistor
- $R_{PU}$  is the value of the external pullup resistor
- 4.5kΩ is the counting the variation of the serial resistor 4kΩ in the I/O line.

### 7.2.3 Application Curve



**Figure 7-3. Level-Translation of a 2.5MHz Signal**

### 7.3 Power Supply Recommendations

During operation, ensure that  $V_{CCA} \leq V_{CCB}$  at all times. During power up sequencing,  $V_{CCA} \geq V_{CCB}$  does not damage the device, so any power supply can be ramped up first. The TXB0101 has circuitry that disables all output ports when either  $V_{CC}$  is switched off ( $V_{CCA/B} = 0V$ ). The output-enable (OE) input circuit is designed so that it is supplied by  $V_{CCA}$  and when the (OE) input is low, all outputs are placed in the high-impedance state.

To confirm the high-impedance state of the outputs during power up or power down, the OE input pin must be tied to GND through a pulldown resistor and must not be enabled until  $V_{CCA}$  and  $V_{CCB}$  are fully ramped and stable. The minimum value of the pulldown resistor to ground is determined by the current-sourcing capability of the driver

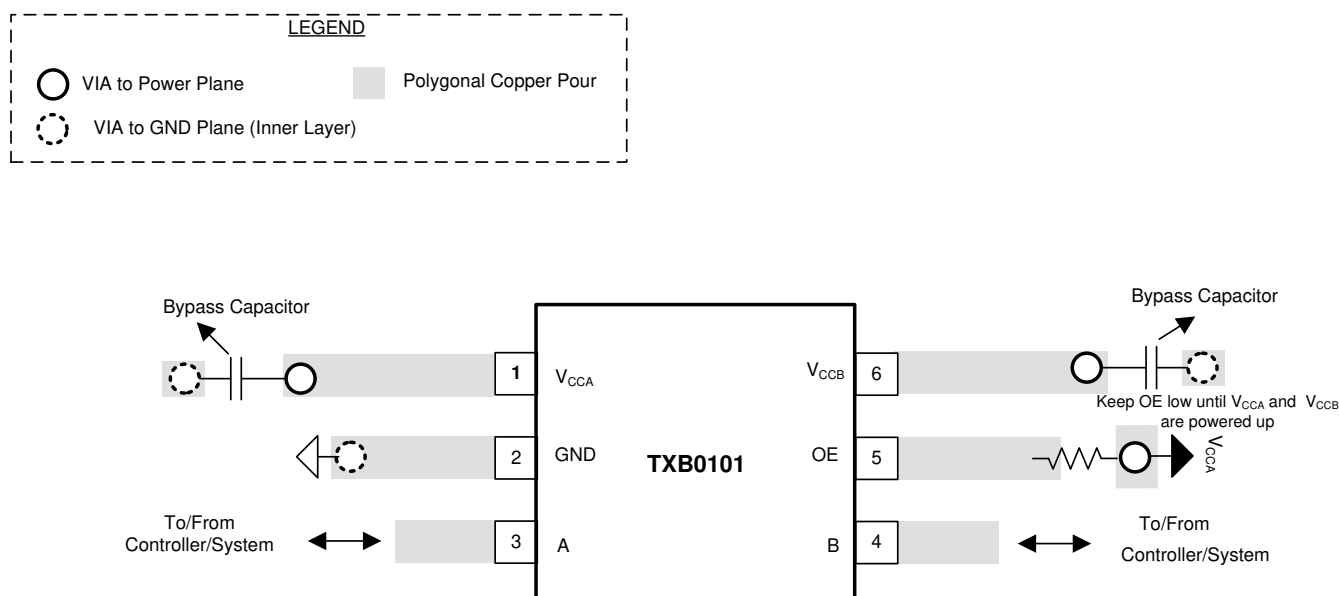
## 7.4 Layout

### 7.4.1 Layout Guidelines

For device reliability, the following common printed-circuit board layout guidelines are recommended.

- Bypass capacitors should be used on power supplies, and should be placed as close as possible to the  $V_{CCA}$ ,  $V_{CCB}$  pin and GND pin.
- Short trace lengths should be used to avoid excessive loading.
- PCB signal trace-lengths must be kept short enough so that the round-trip delay of any reflection is less than the one shot duration, approximately 10ns, making sure that any reflection encounters low impedance at the source driver.

### 7.4.2 Layout Example



**Figure 7-4. Layout Example Recommendation**

## 8 Device and Documentation Support

### 8.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 8.2 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 8.3 Trademarks

NanoFree™ is a trademark of Texas Instruments.

TI E2E™ is a trademark of Texas Instruments.

All trademarks are the property of their respective owners.

### 8.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 8.5 Glossary

#### [TI Glossary](#)

This glossary lists and explains terms, acronyms, and definitions.

## 9 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

### Changes from Revision E (March 2023) to Revision F (September 2025) Page

- Added DRY package information throughout the document..... 1

### Changes from Revision D (March 2017) to Revision E (March 2023) Page

- Changed the Body Size for YZP package from: 1.1mm × 1.20mm to: 0.9mm × 1.40mm in the *Packaging Information* table ..... 1
- Changed Note 1 in the *Absolute Maximum Ratings* ..... 5

### Changes from Revision C (June 2015) to Revision D (March 2017) Page

- Added Absolute maximum junction temperature,  $T_J$  in *Absolute Maximum Ratings* ..... 5
- Added TXB0101 Port A and Port B specifications in *ESD Ratings* table..... 5
- Added *Receiving Notification of Documentation Updates* section..... 22

### Changes from Revision B (May 2012) to Revision C (June 2015) Page

- Added *Pin Configuration and Functions* section, *ESD Ratings* table, *Feature Description* section, *Device Functional Modes*, *Application and Implementation* section, *Power Supply Recommendations* section, *Layout* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section ..... 1
- Removed *Ordering Information* table ..... 1

### Changes from Revision A (November 2008) to Revision B (March 2012) Page

- Added notes to pin out graphics..... 3

## 10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">TXB0101DBVR</a>	Active	Production	SOT-23 (DBV)   6	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(NFCF, NFCR)
TXB0101DBVR.A	Active	Production	SOT-23 (DBV)   6	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(NFCF, NFCR)
TXB0101DBVR.B	Active	Production	SOT-23 (DBV)   6	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(NFCF, NFCR)
TXB0101DBVRG4	Active	Production	SOT-23 (DBV)   6	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	NFCR
TXB0101DBVRG4.A	Active	Production	SOT-23 (DBV)   6	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	NFCR
TXB0101DBVRG4.B	Active	Production	SOT-23 (DBV)   6	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	NFCR
<a href="#">TXB0101DBVT</a>	Active	Production	SOT-23 (DBV)   6	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(NFCF, NFCR)
TXB0101DBVT.B	Active	Production	SOT-23 (DBV)   6	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(NFCF, NFCR)
TXB0101DBVTG4	Active	Production	SOT-23 (DBV)   6	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(NFCF, NFCR)
<a href="#">TXB0101DCKR</a>	Active	Production	SC70 (DCK)   6	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	27O
TXB0101DCKR.A	Active	Production	SC70 (DCK)   6	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	27O
TXB0101DCKR.B	Active	Production	SC70 (DCK)   6	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	27O
TXB0101DCKRG4	Active	Production	SC70 (DCK)   6	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	27O
<a href="#">TXB0101DCKT</a>	Active	Production	SC70 (DCK)   6	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-	27O
TXB0101DCKT.B	Active	Production	SC70 (DCK)   6	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	27O
TXB0101DCKTG4	Active	Production	SC70 (DCK)   6	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	27O
<a href="#">TXB0101DRLR</a>	Active	Production	SOT-5X3 (DRL)   6	4000   LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	27R
TXB0101DRLR.A	Active	Production	SOT-5X3 (DRL)   6	4000   LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	27R
TXB0101DRLR.B	Active	Production	SOT-5X3 (DRL)   6	4000   LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	27R
<a href="#">TXB0101DRLT</a>	Active	Production	SOT-5X3 (DRL)   6	250   SMALL T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	27R
TXB0101DRLT.B	Active	Production	SOT-5X3 (DRL)   6	250   SMALL T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	27R
<a href="#">TXB0101YZPR</a>	Active	Production	DSBGA (YZP)   6	3000   LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	27N
TXB0101YZPR.B	Active	Production	DSBGA (YZP)   6	3000   LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	27N

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.



<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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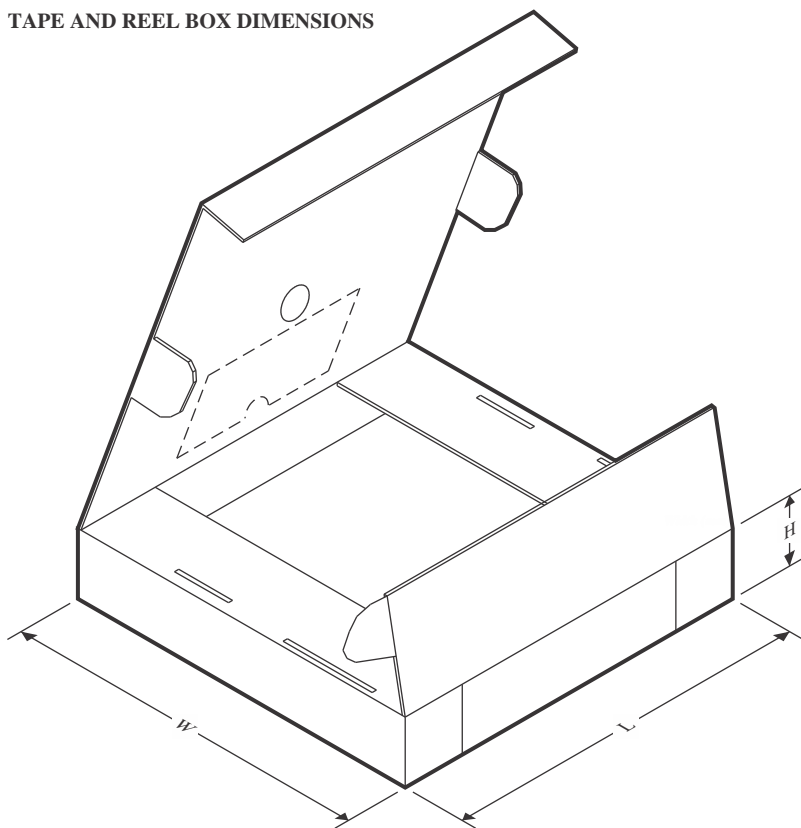
## TAPE AND REEL INFORMATION



\*All dimensions are nominal

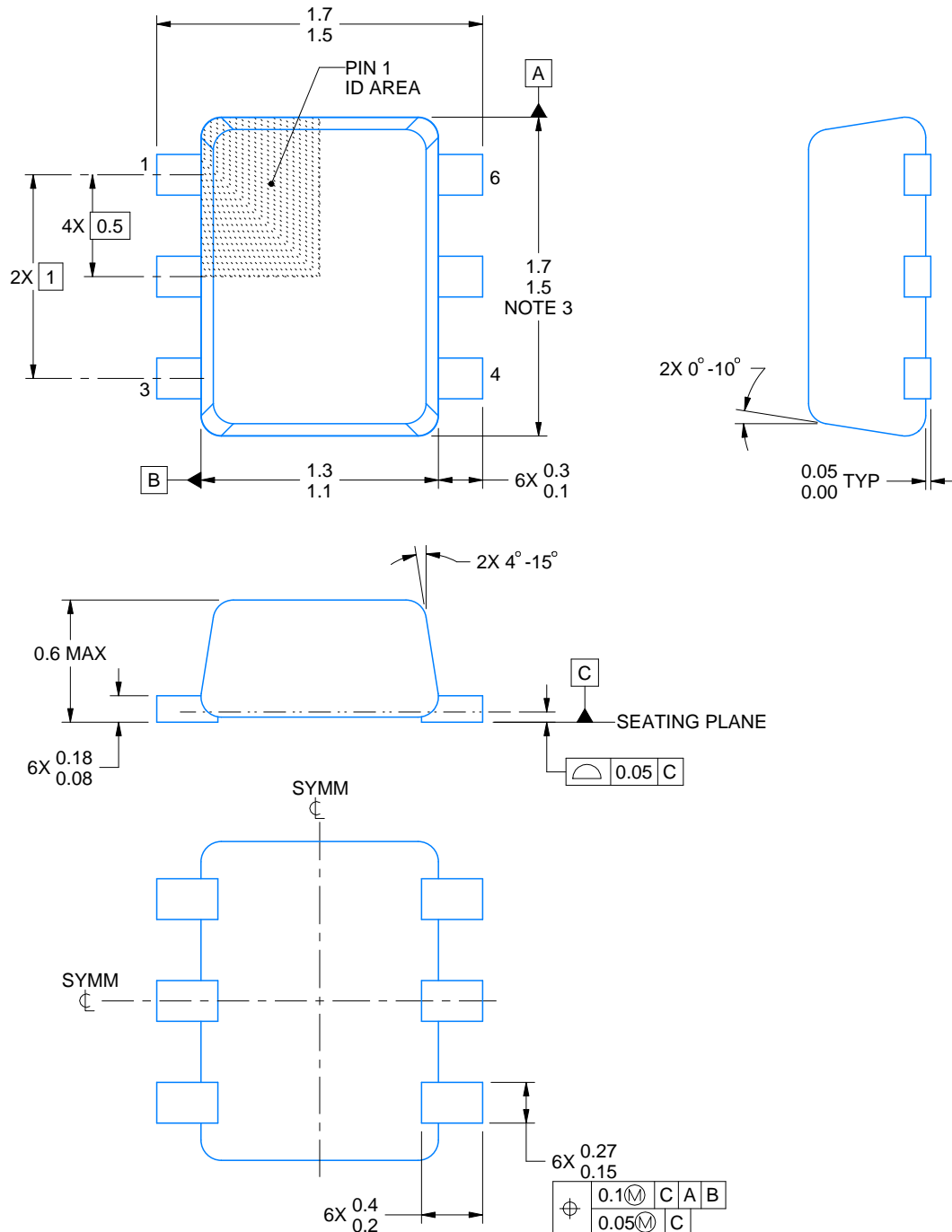
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TXB0101DBVR	SOT-23	DBV	6	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
TXB0101DBVRG4	SOT-23	DBV	6	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
TXB0101DBVT	SOT-23	DBV	6	250	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
TXB0101DCKR	SC70	DCK	6	3000	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TXB0101DCKT	SC70	DCK	6	250	179.0	8.4	2.2	2.5	1.2	4.0	8.0	Q3
TXB0101DRLR	SOT-5X3	DRL	6	4000	180.0	8.4	1.98	1.78	0.69	4.0	8.0	Q3
TXB0101DRLT	SOT-5X3	DRL	6	250	180.0	8.4	1.98	1.78	0.69	4.0	8.0	Q3
TXB0101YZPR	DSBGA	YZP	6	3000	178.0	9.2	1.02	1.52	0.63	4.0	8.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TXB0101DBVR	SOT-23	DBV	6	3000	202.0	201.0	28.0
TXB0101DBVRG4	SOT-23	DBV	6	3000	202.0	201.0	28.0
TXB0101DBVT	SOT-23	DBV	6	250	202.0	201.0	28.0
TXB0101DCKR	SC70	DCK	6	3000	200.0	183.0	25.0
TXB0101DCKT	SC70	DCK	6	250	203.0	203.0	35.0
TXB0101DRLR	SOT-5X3	DRL	6	4000	202.0	201.0	28.0
TXB0101DRLT	SOT-5X3	DRL	6	250	202.0	201.0	28.0
TXB0101YZPR	DSBGA	YZP	6	3000	220.0	220.0	35.0



4223266/F 11/2024

## NOTES:

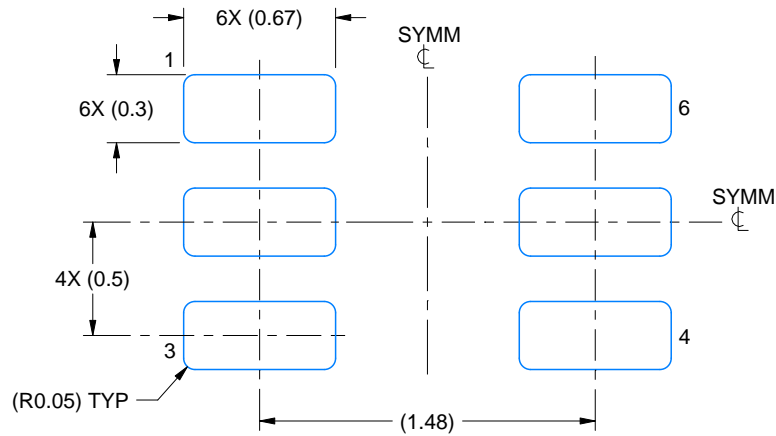
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-293 Variation UAAD

# EXAMPLE BOARD LAYOUT

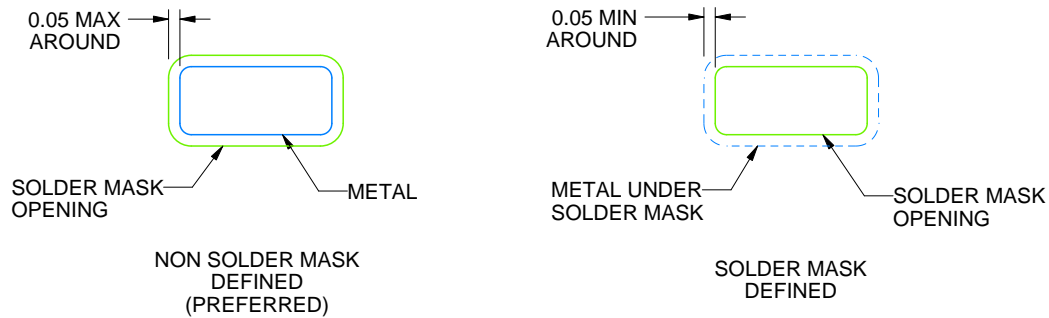
DRL0006A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



LAND PATTERN EXAMPLE  
SCALE:30X



SOLDERMASK DETAILS

4223266/F 11/2024

NOTES: (continued)

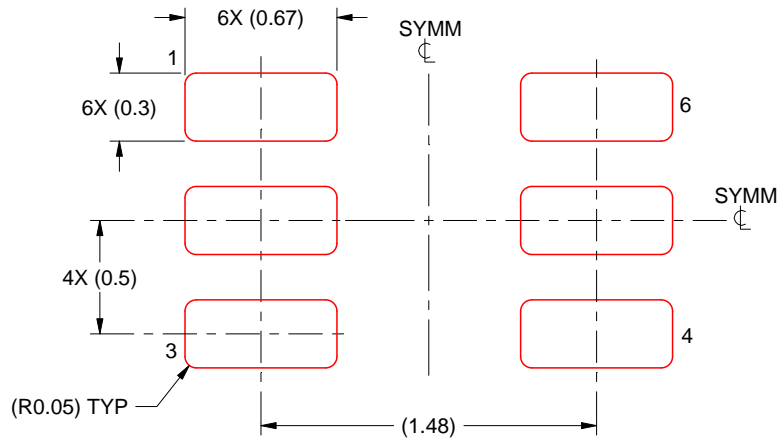
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
7. Land pattern design aligns to IPC-610, Bottom Termination Component (BTC) solder joint inspection criteria.

# EXAMPLE STENCIL DESIGN

DRL0006A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



SOLDER PASTE EXAMPLE  
BASED ON 0.1 mm THICK STENCIL  
SCALE:30X

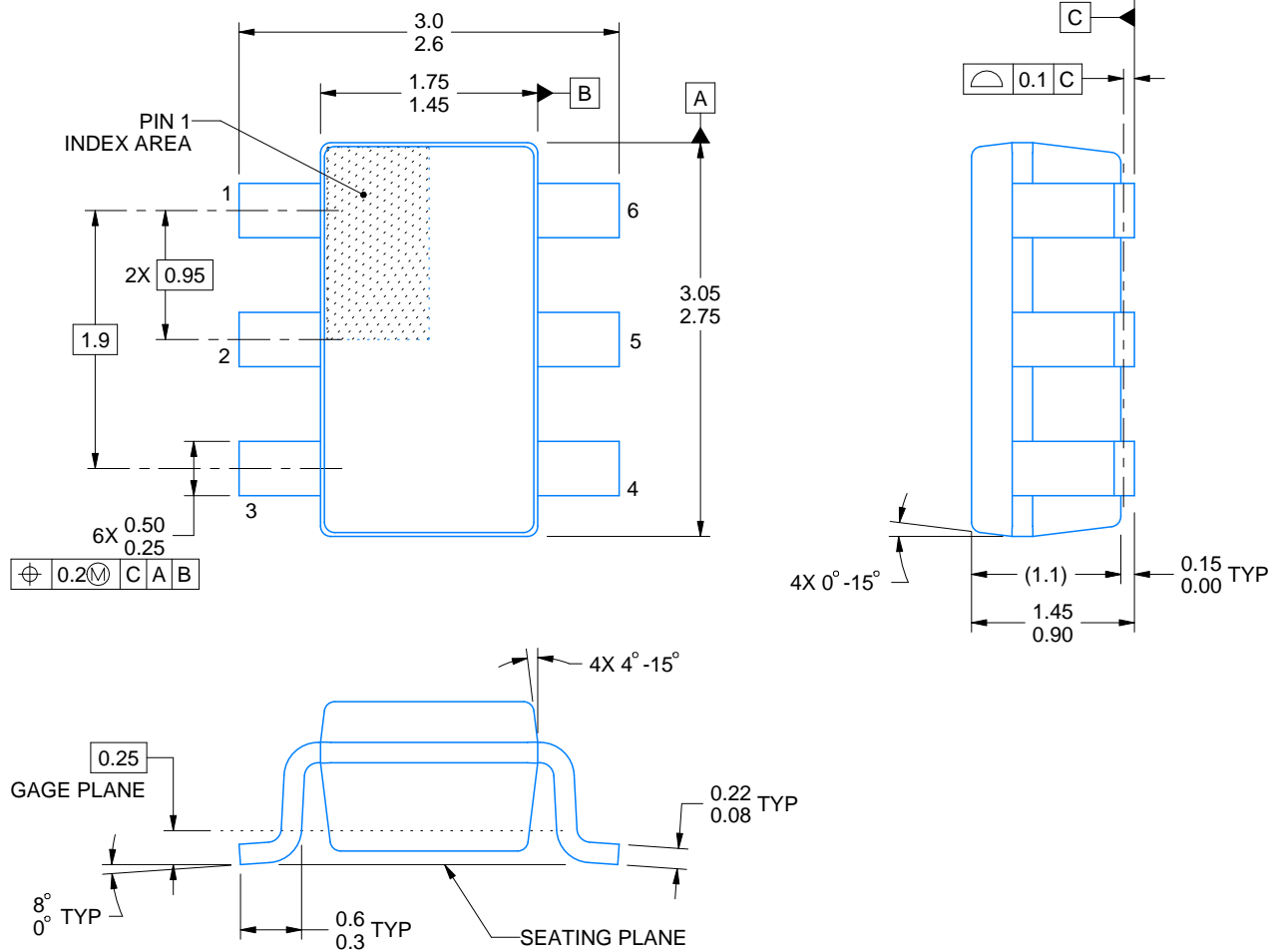
4223266/F 11/2024

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

**DBV0006A****PACKAGE OUTLINE****SOT-23 - 1.45 mm max height**

SMALL OUTLINE TRANSISTOR



4214840/G 08/2024

**NOTES:**

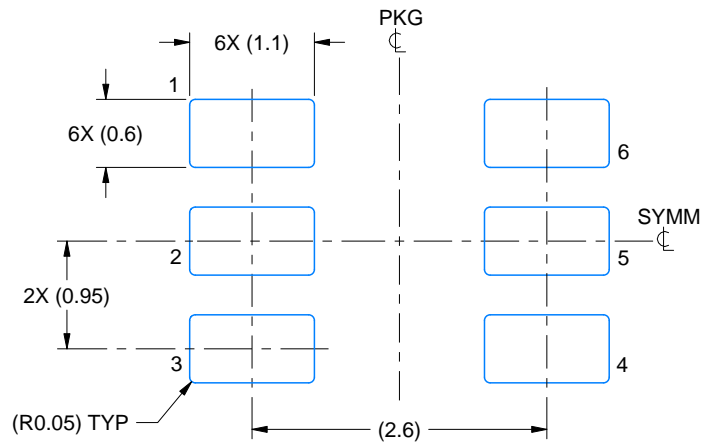
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.25 per side.
4. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
5. Reference JEDEC MO-178.

# EXAMPLE BOARD LAYOUT

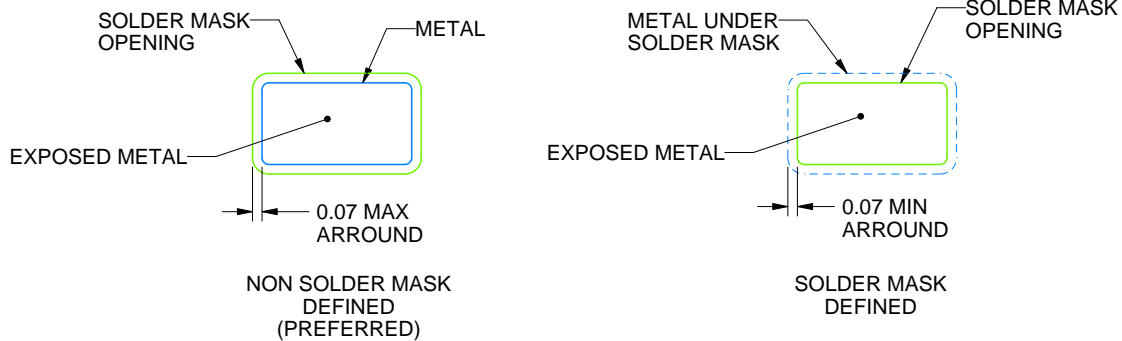
DBV0006A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:15X



SOLDER MASK DETAILS

4214840/G 08/2024

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

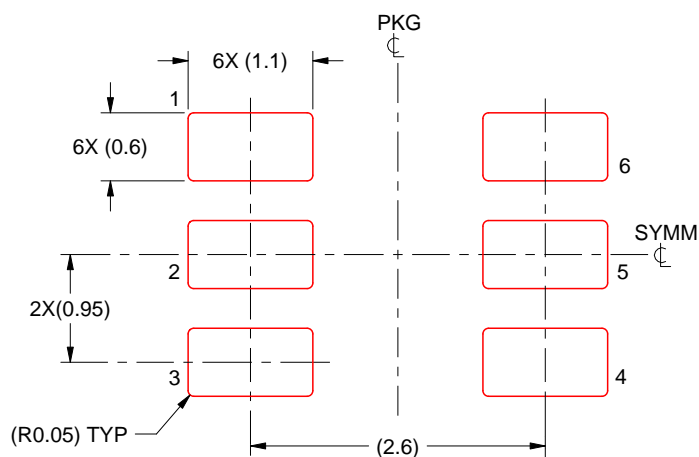


## EXAMPLE STENCIL DESIGN

DBV0006A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:15X

4214840/G 08/2024

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

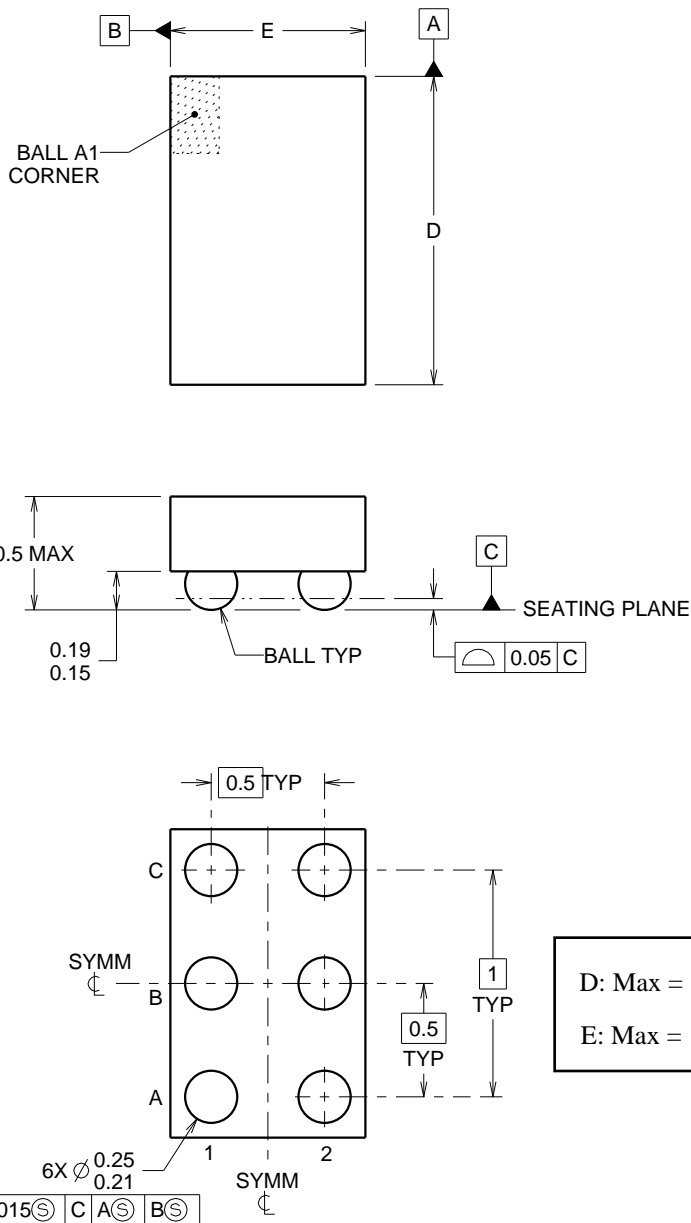
YZP0006



# PACKAGE OUTLINE

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



4219524/A 06/2014

## NOTES:

NanoFree Is a trademark of Texas Instruments.

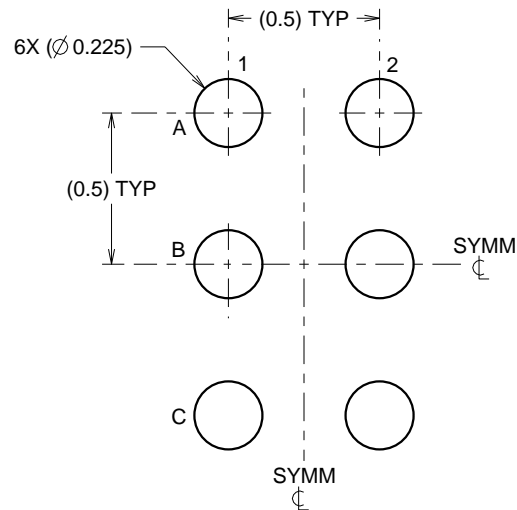
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. NanoFree™ package configuration.

# EXAMPLE BOARD LAYOUT

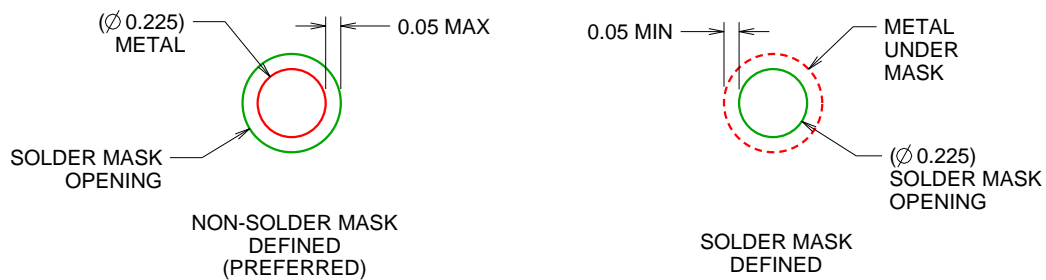
YZP0006

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE  
SCALE:40X



SOLDER MASK DETAILS  
NOT TO SCALE

4219524/A 06/2014

NOTES: (continued)

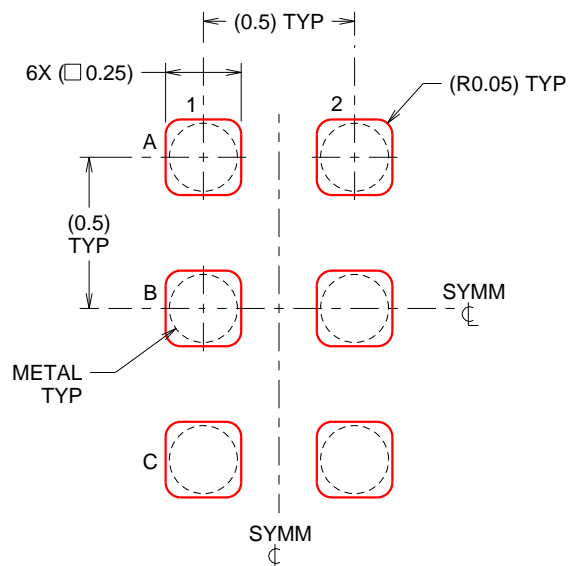
4. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints.  
For more information, see Texas Instruments literature number SBVA017 ([www.ti.com/lit/sbva017](http://www.ti.com/lit/sbva017)).

## EXAMPLE STENCIL DESIGN

YZP0006

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



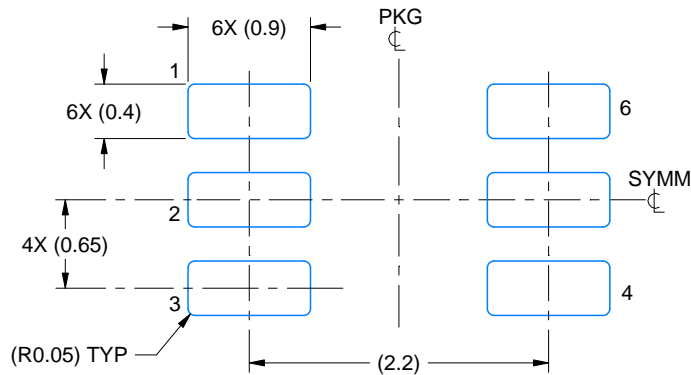
SOLDER PASTE EXAMPLE  
BASED ON 0.1 mm THICK STENCIL  
SCALE:40X

4219524/A 06/2014

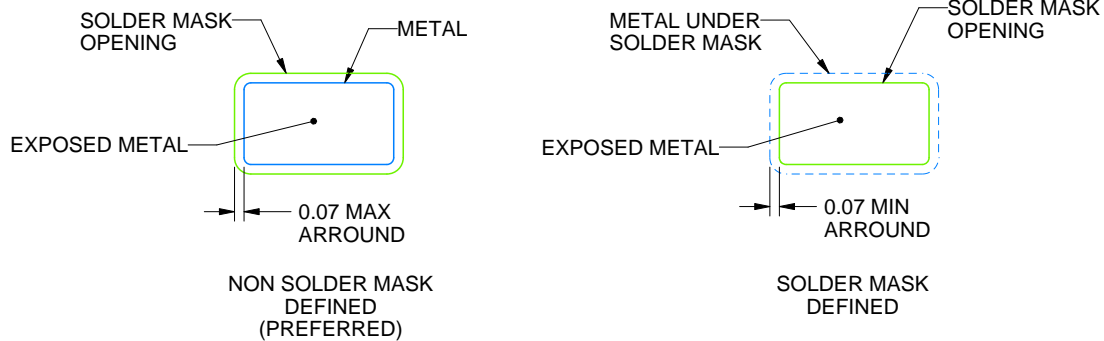
NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.





LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:18X

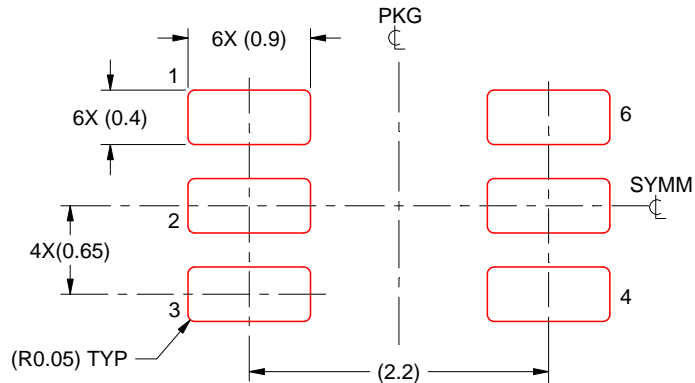


SOLDER MASK DETAILS

4214835/D 11/2024

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE  
BASED ON 0.125 THICK STENCIL  
SCALE:18X

4214835/D 11/2024

### NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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